

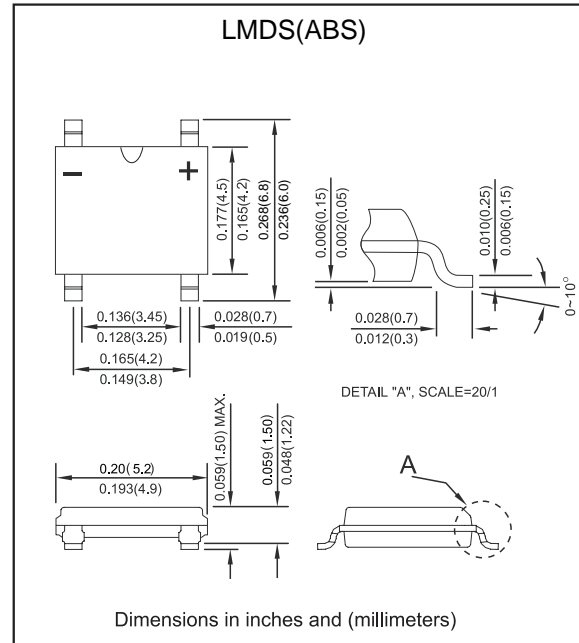
Features

- Glass passivated junction
- Ideal for printed circuit board
- Reliable low cost construction utilizing molded plastic technique
- High temperature soldering guaranteed: 260°C / 10 seconds / 0.375" (9.5mm) lead length at 5 lbs., (2.3 kg) tension
- High surge current capability
- Compliant to Halogen-free

Mechanical data

- Epoxy: UL94-V0 rated flame retardant
- Case : Molded plastic, LMDS(ABS)
- Terminals : Solder plated, solderable per MIL-STD-202, Method 208
- Polarity : marked on body
- Mounting Position : Any

Package outline



Maximum ratings and Electrical Characteristics (AT T_A=25°C unless otherwise noted)

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Forward rectified current	On aluminum substrate	I _o			2.0	A
Forward surge current	8.3ms single half sine-wave superimposed on rate load (JEDEC methode)	I _{FSM}			50	A
Reverse current	V _R = V _{RRM} T _J = 25°C	I _R			5.0	μA
	V _R = V _{RRM} T _J = 125°C				200	
Typical Thermal resistance	Junction to ambient (Note 2)	R _{θJA}		62.5		°C/W
Typical Junction Capacitance	(Note 3)	C _j		30		pF
Storage temperature		T _{STG}	-55		+150	°C

SYMBOLS	V _{RRM} ^{*1} (V)	V _{RMS} ^{*2} (V)	V _R ^{*3} (V)	t _{rr} ^{*4} (ns)	V _F ^{*5} (V)	Operating temperature T _J , (°C)
RABS22	200	140	200	150	1.30	-55 to +150
RABS24	400	280	400			
RABS26	600	420	600			
RABS28	800	560	800			
RABS210	1000	700	1000			

- *1 Repetitive peak reverse voltage
- *2 RMS voltage
- *3 Continuous reverse voltage
- *4 Maximum Reverse recovery time, note 1
- *5 Maximum forward voltage@I_F=2.0A

Note 1. Reverse recovery time test condition, I_F=0.5A, I_R=1.0A, I_{RR}=0.25A
 2. Mounted on glass epoxy PC board with 4*1.5**1.5*(3.81**3.81cm)copper pad
 3. Measured at 1 MHz and applied reverse voltage of 4 VD.C

Rating and characteristic curves (RABS22 THRU RABS210)

Fig.1 Average Rectified Output Current Derating Curve

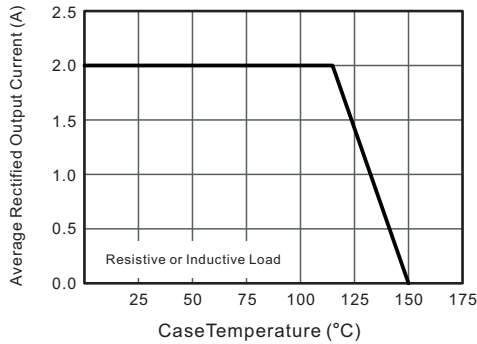


Fig.2 Typical Reverse Characteristics

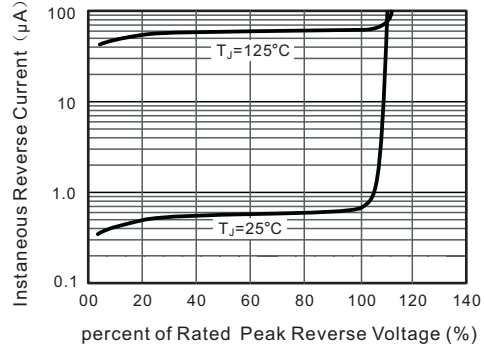


Fig.3 Typical Instantaneous Forward Characteristics

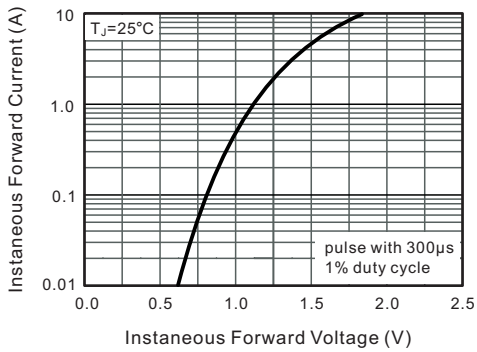


Fig.4 Typical Junction Capacitance

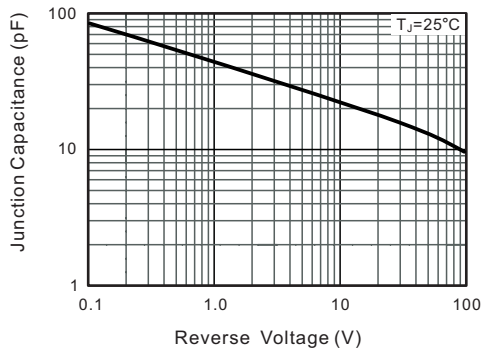
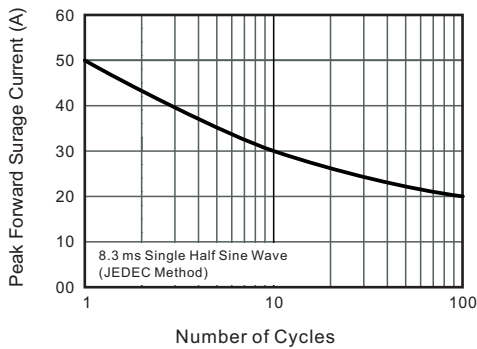
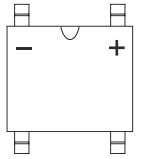
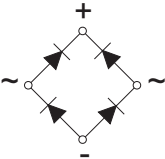


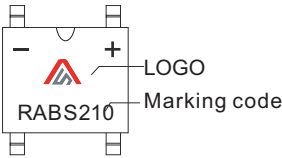
Fig.5 Maximum Non-Repetitive Peak Forward Surge Current



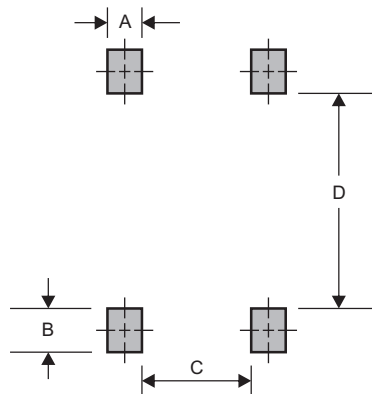
Pinning information

Simplified outline	Symbol
	

Marking

Type number	Marking code	Example
RABS22	RABS22	
RABS24	RABS24	
RABS26	RABS26	
RABS28	RABS28	
RABS210	RABS210	

Suggested solder pad layout



Dimensions in inches and (millimeters)

PACKAGE	A	B	C	D
LMDS/ABS	0.024 (0.60)	0.024 (0.60)	0.132 (3.35)	0.193 (4.90)